

電動化対応材料

Electrification materials

材料技術を進化させ、熱、絶縁等に貢献

Material technology is advanced to contribute the control of thermal and electrical insulation, etc.

熱伝導・絶縁性

Thermal conduction / Electrical insulation

樹脂バイメタル材の混練技術を応用
Application of kneading technology used in sliding bearing

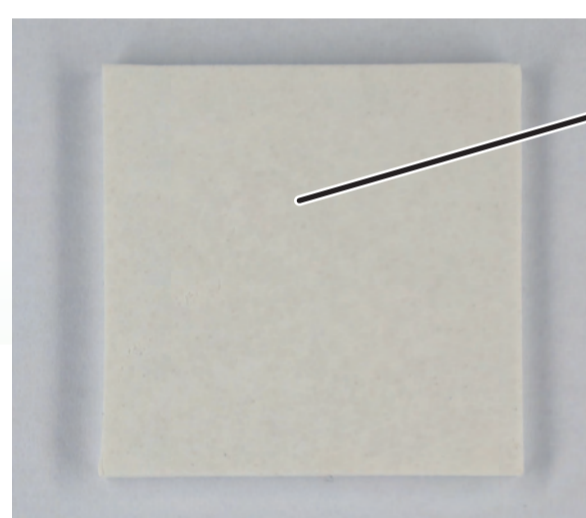
開発中 Under development

高热伝導率 シート型材料

Sheet type material with high thermal conductivity



詳細はこちらをクリック



シート型放熱材料 Heat transfer material

フィラー最適化
(種類・粒径・配合量)

Optimization of additives
(types, particle size, additive amount)

開発目標
Development target

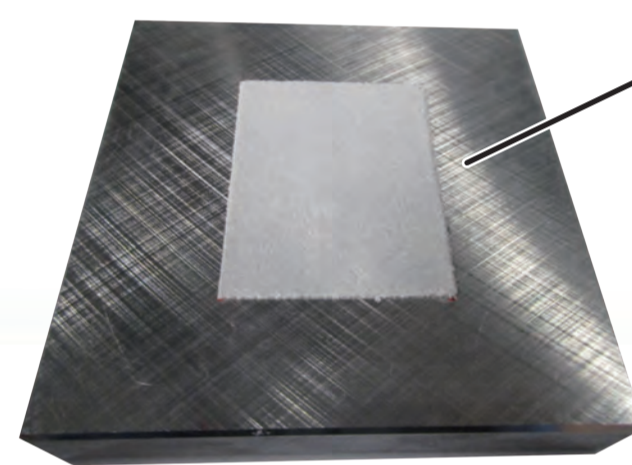
熱伝導率 10W/m・K
Thermal conductivity

高热伝導率 接着型材料

Adhesive glue type material with high thermal conductivity



詳細はこちらをクリック



接着剤型放熱材料 Heat transfer material

フィラー最適化
(種類・粒径・配合量)

Optimization of additives
(types, particle size, additive amount)

開発目標
Development target

熱伝導率 6W/m・K Thermal conductivity
密着強度 10MPa Adhesion strength

電磁波遮蔽

Electromagnetic wave-shielding

すべり軸受のめっき技術を応用
Application of plating technology using sliding bearing

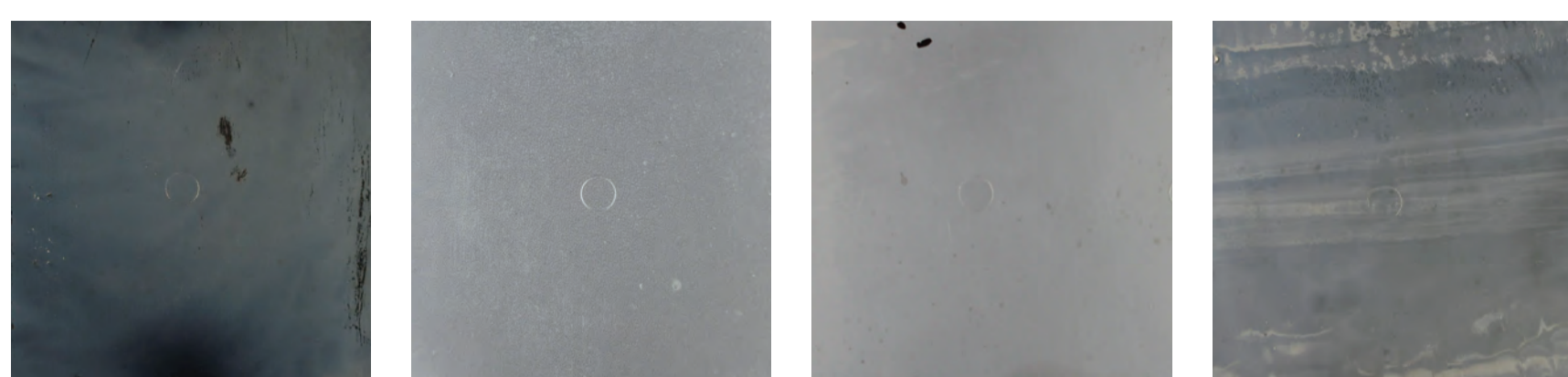
開発中
Under development

低周波数帯シールド めっき

Plating shield for low frequency band



詳細はこちらをクリック



Ni/Cu

In/Cu

Bi/Cu

Bi-Sb/Cu

めっき複層化及び合金化 重クロム酸レス前処理
Multilayer plating and alloy plating Dichromic acid free pretreatment

開発目標
Development target

シールド 60dB
Shielding performance

導電性・耐食性

Electrical conductivity / Corrosion resistance

軸受の耐食性向上の考えを応用
Application of improvement technology of corrosion resistance using bearing

開発中
Under development

高耐久 DLC

DLC with high durability performance



詳細はこちらをクリック



中間層付DLC
DLC with middle layer

DLC,中間層に元素添加
DLC and middle layer doped element

開発目標
Development target

接触抵抗 $2\text{m}\Omega\cdot\text{cm}^2$
Contact electric resistance
腐食電流密度 $0.1\ \mu\text{A}/\text{cm}^2$
Corrosion current density